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MD240128A6W-FPTLW 240 x 128		LCD Module				
	Specification					
Version: 2		Date: 25/10/2020				
	Revision					
1	29/07/2020	First Issue				
2	21/10/2020	Add Interface				

Display F	Display Features				
Resolution	240 x 128				
Appearance	Black on White				
Logic Voltage	-3.3V		1		
Interface	Parallel	U W R	ROHS		
Font Set	N/A		NoHS ompliant		
Display Mode	Transflective		mphant		
LC Type	FSTN				
Module Size	140.00 x 84.00 x 9.70 mm				
Operating Temperature	-20°C ~ +70°C				
Construction	СОВ	Box Quantity	Weight / Display		
LED Backlight	White				
DESIGN	MANUFACTUR	E SUP	PLY		

* - For full design functionality, please use this specification in conjunction with the ST7586S specification.(Provided Separately)

Display Accessories					
Part Number	Description				

Optional Variants					
Appearances	Voltage				

General Specification

The Features is described as follow:

■ Module dimension: 140.0 x 84.0 x 9.7 mm

■ View area: 114.0 x 64.0 mm

■ Active area: 107.98 x 57.58 mm

■ Number of dots: 240 x 128

■ Dot size: 0.43 x 0.43 mm

■ Dot pitch: 0.45 x 0.45 mm

■ LCD type: FSTN Positive Transflective

■ Duty: 1/128Duty , 1/12Bias

■ View direction: 6 o'clock

■ Backlight Type: LED White

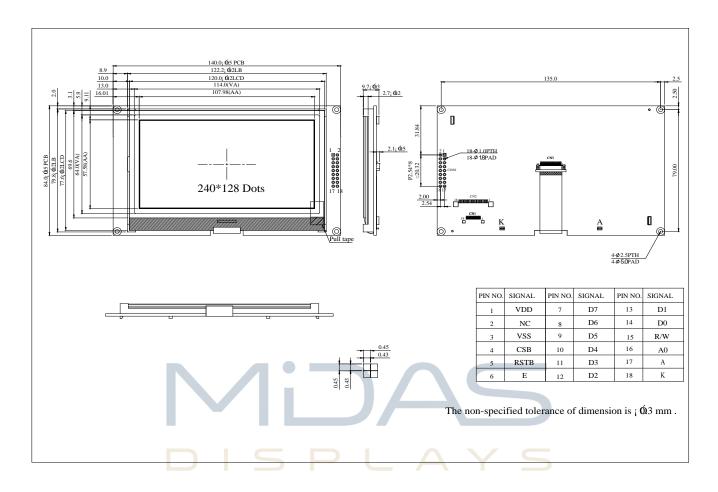
■ IC: ST7586S

■ Interface:68 series

Interface Pin Function

Pin	Symbol	Description
1	VDD	Power supply
2	NC	No connection
3	VSS	Ground
4	CSB	Chip select input pin CSB="L": This chip is selected and the MPU interface is active CSB="H": This chip is not selected and the MPU interface is disabled (D[7:0] are high impedance)
5	RSTB	Reset input pin. When RSTB is "L", internal initialization procedure is executed
6	E	Read / Write control input pin. R/W = "H": When E is "H", data bus is in output status. R/W = "L": The data are latched at the falling edge of the E signal.
7~14	D7~D0	The bi-directional data bus of the MPU interface. When CSB is "H", they are high impedance
15	R/W DESI	Read / Write control input pin R/W = "H" : read R/W = "L" : write NUFACTURE • SUPPLY
16	A0	The function of this pin is different in parallel and serial interface In parallel interface: A0 is register selection input A0 = "H": inputs on data bus are display data A0 = "L": inputs on data bus are command
17	А	LED+
18	K	LED-

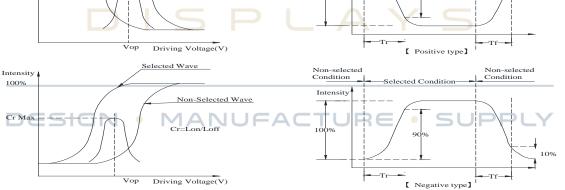
Contour Drawing



Optical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
	θ	CR≧2	0	_	30	ψ= 180°
View Angle	θ	CR≧2	0	_	60	ψ= 0°
View Angle	θ	CR≧2	0	_	45	ψ= 90°
	θ	CR≧2	0	_	45	ψ= 270°
Contrast Ratio	CR	_	_	5	_	_
	T rise	_	_	200	300	ms
Response Time	T fall	_	_	250	350	ms

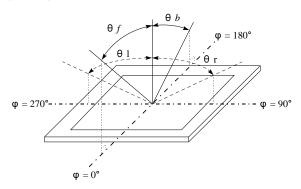




Conditions:

Frame Frequency: 64 HZ Driving Waveform: 1/N duty, 1/a bias

Definition of viewing angle(CR≧2)



Absolute Maximum Ratings

Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	Тор	-20	_	+70	°C
Storage Temperature	T _{ST}	-30	_	+80	°C
Digital Power Supply Voltage	VDDI	-0.3	_	3.6	V
Analog Power supply voltage	VDDA	-0.3	_	3.6	V
LCD Power supply voltage	V0-XV0	-0.3	_	19	V
LCD Power supply voltage	VG	-0.3	_	5.5	V

Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For	V _{DD} -V _{SS}		3.0	3.3	3.6	V
Logic	V DD- V SS		3.0	5.5	5.0	V
		Ta=-20°C	_	_	_	V
Supply Voltage For LCM	MOPNL	Ta=25℃	14.8	15.0	45.2P	LV
		Ta=+70℃	_	_	_	V
Input High Volt.	Vih	_	0.7V _{DD}	_	V _{DD}	V
Input Low Volt.	VıL	_	Vss	_	0.3 V _{DD}	V
Output High Volt.	Vон	_	0.8 V _{DD}	_	V_{DD}	V
Output Low Volt.	Vol	_	Vss		0.2V _{DD}	V
Supply Current	l _{DD}	V _{DD} =3.3V	_	2.0	4.0	mA

Please kindly consider to design the Vop to be adjustable while programing the software to match LCD contrast tolerance.

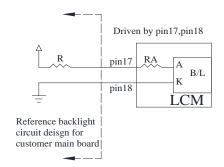
Backlight Information

Specification

Parameter	Symbol	Min	Тур	Max	Unit	Test Condition
Supply Current	ILED	-	144	180	mA	V=3.5V
Supply Voltage	V	3.4	3.5	3.6	V	_
Reverse Voltage	VR	_	_	5	V	_
Color	Х	0.244	0.264	0.284		
coordinate	Y	0.264	0.284	0.304	_	ILED=144mA
Luminance	11/	750	040		a al /1002	ILED=144mA
(Without LCD)	IV	750	940		ca/m²	ILED=144MA
LED Life Time					/ (ILED=144mA
(For Reference	_		50K	_	Hr.	25℃,50-60%RH,
only)		5	PI	_ /	Y	(Note 1)
Color	White					

Note: The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).

Note 1:50K hours is only an estimate for reference.



Reliability

Content of Reliability Test (Wide temperature, -20°C~70°C)

	Environmental Test							
Test Item	Content of Test	Test Condition	Note					
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°C 96hrs	2					
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30°C 96hrs	1,2					
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 96hrs						
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 96hrs	1					
High Temperature/ Humidity storage	The module should be allowed to stand at 60°C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C,90%RH 96hrs	1,2					
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation -20°C 25°C 70°C 30min 5min 30min 1 cycle	-20°C/70°C 10 cycles						
	ISPLAY	Total fixed amplitude : 1.5mm						
Vibration test	Endurance test applying the vibration during transportation and using.	Vibration Frequency: 10~55Hz One cycle 60 seconds to 3	3					
Static electricity test	Endurance test applying the electric stress to the terminal.	directions of X,Y,Z for Each 15 minutes VS=±600V(contact), ±800v(air), RS=330 Ω CS=150pF 10 times						

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.

Inspection specification

NO	Item			Criterion		AQL	
01	Electrical Testing	 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect. 2.1 White and black spots on display ≤0.25mm, no more than 					
02	Black or white spots on LCD (display only)	three white or	three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within				
03	LCD black spots, white spots, contamination	3.1 Round type : $A = (x + y)/2$ $X \leftarrow \frac{1}{4}$		SIZE Φ≦0.10 0.10<Φ≦0.20 0.20<Φ≦0.25 0.25<Φ	Acceptable Q TY Accept no dense 2 1 0	2.5	
	(non-display)	→ L W	s followin Length L≦3.0 L≦2.5	yidth W≤0.02 0.02 <w≤0.03 0.03<w≤0.05="" 0.05<w<="" td=""><td>Acceptable Q TY Accept no dense 2 As round type</td><td>2.5</td></w≤0.03>	Acceptable Q TY Accept no dense 2 As round type	2.5	
04	Polarizer bubbles	If bubbles are visi judge using black specifications, not to find, must chec specify direction.	spot t easy	Size Φ $Φ \le 0.20$ $0.20 < Φ \le 0.50$ $0.50 < Φ \le 1.00$ $1.00 < Φ$ Total Q TY	Acceptable Q TY Accept no dense 3 2 0 3	2.5	

NO	Item	Criterion					
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination					
		Symbols Define: x: Chip length y: 0	Chip width z: Chip Glass thickness a: LCI	thickness O side length			
06	Chipped glass	z: Chip thickness $Z \le 1/2t$ $1/2t < z \le 2t$ ① If there are 2 or more $6.1.2 \text{ Corner crack:}$	y: Chip width Not over viewing area Not exceed 1/3k chips, x is total length of	x: Chip length x≤1/8a x≤1/8a of each chip.	2.5		
	DESIGI	z: Chip thickness Z≦1/2t	y: Chip width Not over viewing	x: Chip length x≤1/8a			
		1/04 / = / 04	area	v < 1/00			
		1/2t < z ≦ 2t	Not exceed 1/3k	x≦1/8a			
		⊙If there are 2 or more	chips, x is the total leng	gtn of each chip.			

NO	Item	Criterion					
	Glass	Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 6.2 Protrusion over terminal: 6.2.1 Chip on electrode pad:					
06		$\begin{array}{ c c c c c c }\hline y: Chip \ width & x: Chip \ length & z: Chip \ thickness \\\hline y \le 0.5mm & x \le 1/8a & 0 < z \le t \\\hline 6.2.2 \ Non-conductive \ portion: \\\hline \\ y & X & X & X & X \\\hline \end{array}$					
	DES	y: Chip width x: Chip length z: Chip thickness $y \le L$ $x \le 1/8a$ $0 < z \le t$ Olf the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. Olf the product will be heat sealed by the customer, the alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack. y: width x: length $y \le 1/3L$ $x \le a$					

NO	Item	Criterion	AQL		
07	Cracked glass	The LCD with extensive crack is not acceptable.			
08	Backlight elements	 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. 			
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.9.2 Bezel must comply with job specifications.			
		 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than 	2.5 2.5 0.65 2.5		
10	PCB · COB	three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts.	2.5 0.65		
	DESIGN	 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB X * Y<=2mm2 	0.65 2.5 2.5		
11	Soldering	 11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB. 	2.5 2.5 2.5 0.65		

NO	Item	Criterion				
NO 12	General appearance	 12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. 12.2 No cracks on interface pin (OLB) of TCP. 12.3 No contamination, solder residue or solder balls on product. 12.4 The IC on the TCP may not be damaged, circuits. 12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever. 12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color. 12.7 Sealant on top of the ITO circuit has not hardened. 12.8 Pin type must match type in specification sheet. 12.9 LCD pin loose or missing pins. 12.10 Product packaging must the same as specified on 	2.5 0.65 2.5 2.5 2.5 2.5 0.65 0.65 0.65			
		12.10 Product packaging must the same as specified on packaging specification sheet.12.11 Product dimension and structure must conform to product				
		specification sheet. 12.12 Visual defect outside of VA is not considered to be rejection.				

Precautions in use of LCD Modules

- (1)Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7) Storage: please storage in anti-static electricity container and clean environment.
- (8) Midas Displays have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9) Midas Displays have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Midas Displays have the right to modify the version.)
- (10) To ensure the stability of the display screen, please apply screen saver after showing 30 mins of fixed display content.
- (11)Please heat up a little the tape sticking on the components when removing it; otherwise the components might be damaged.

Material List of Components for RoHs

1. Midas Displays hereby declares that all of or part of products (with the mark "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A: The Harmful Material List

Material	Cd	Pb	Hg	Cr6+	PBB	PBDE	DEHP	BBP	DBP	DIBP
Limited	100	1000	1000	1000	1000	1000	1000	1000	1000	1000
Value	ppm	ppm	ppm	ppm	ppm	ppm	ppm	ppm	ppm	ppm
Above limited value is set up according to RoHS.										

- 2.Process for RoHS requirement : (only for RoHS inspection)
 - (1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.
 - (2) Heat-resistance temp. :

Reflow: 250°C,30 seconds Max.;

Connector soldering wave or hand soldering: 320°C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. : 235±5°C;

Recommended customer's soldering temp. of connector: 280°C, 3 seconds.



Recommendable Storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module.